



US00D855027S

(12) **United States Design Patent**  
**Okajima et al.**

(10) **Patent No.:** **US D855,027 S**  
(45) **Date of Patent:** **\*\* Jul. 30, 2019**

(54) **COVER OF SEAL CAP FOR REACTION CHAMBER OF SEMICONDUCTOR**

(71) Applicant: **Hitachi Kokusai Electric Inc.**, Tokyo (JP)

(72) Inventors: **Yusaku Okajima**, Tokyo (JP); **Shuhei Saïdo**, Tokyo (JP); **Hidenari Yoshida**, Tokyo (JP)

(73) Assignee: **KOKUSAI ELECTRIC CORPORATION**, Tokyo (JP)

(\*\*) Term: **15 Years**

(21) Appl. No.: **29/649,486**

(22) Filed: **May 30, 2018**

(30) **Foreign Application Priority Data**

Jan. 22, 2018 (JP) ..... 2018-001070

(51) **LOC (11) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**

USPC ..... D13/182, 184, 162; D10/49, 50  
CPC ..... C23C 16/455; C23C 16/45502; C23C 16/45517; C23C 16/4582; C23C 16/4583; C23C 16/4584; C23C 16/4585; C23C 16/4401; C23C 16/4402; C23C 16/4409; H01L 21/50; H01L 21/4817; H01L 21/4871; H01L 23/02; H01L 23/04; H01L 23/12; H01L 23/13; H01L 23/14; H05K 3/30

See application file for complete search history.

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*Primary Examiner* — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Fitch, Even, Tabin & Flannery, LLP

(57) **CLAIM**

The ornamental design for a cover of seal cap for reaction chamber of semiconductor, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top, left side perspective view of a cover of seal cap for reaction chamber of semiconductor showing our new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

FIG. 4 is a right side elevational view thereof;

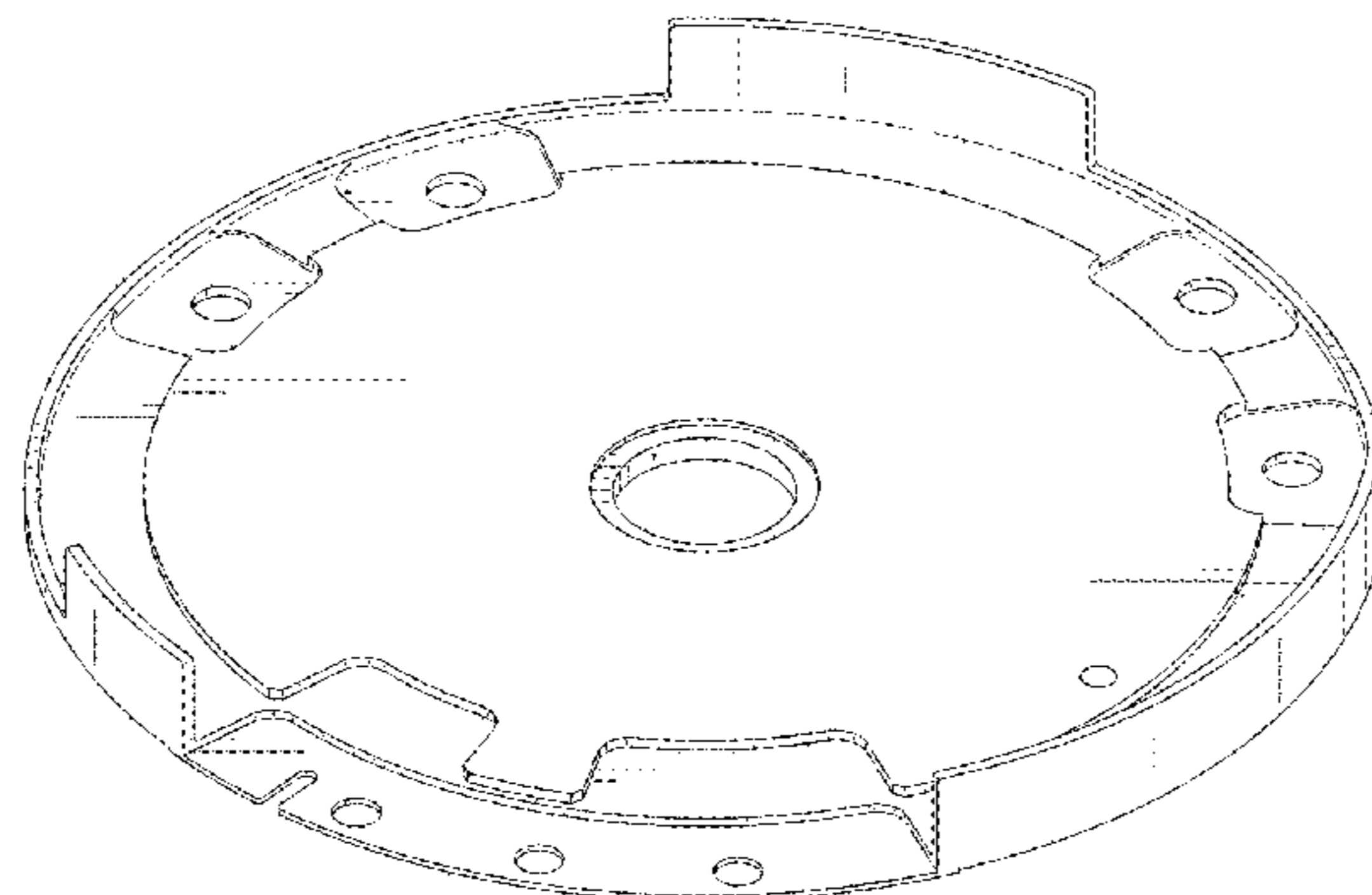
FIG. 5 is a left side elevational view thereof;

FIG. 6 is a top plan view thereof;

FIG. 7 is a bottom plan view thereof; and,

FIG. 8 is a cross sectional view taken along line 8-8 in FIG. 6.

**1 Claim, 5 Drawing Sheets**



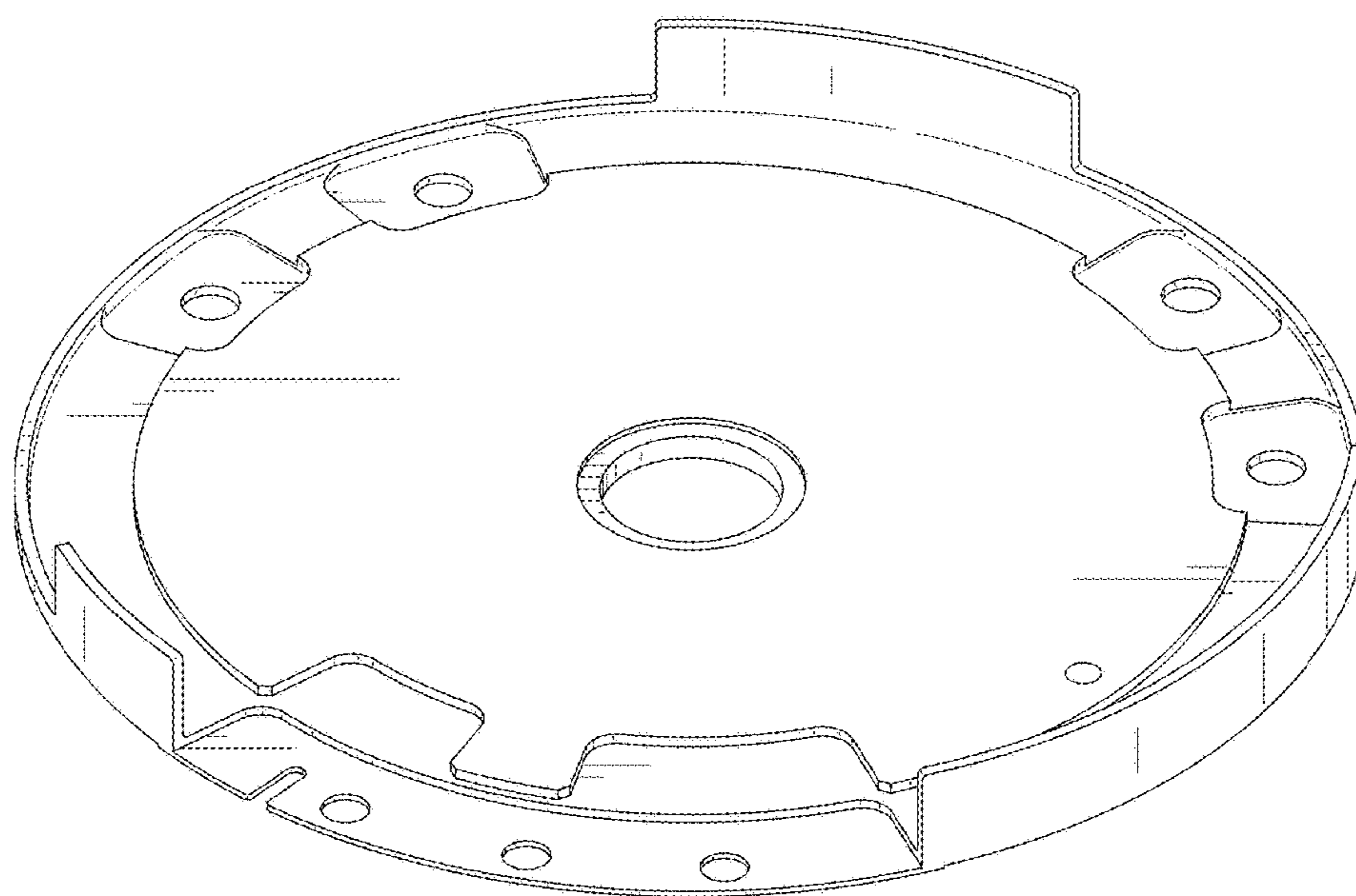


FIG. 1

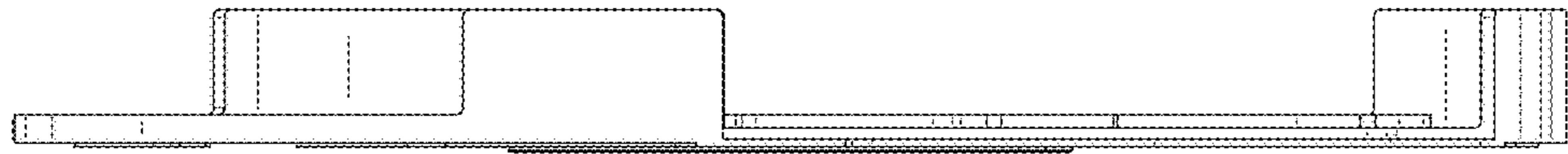


FIG. 2

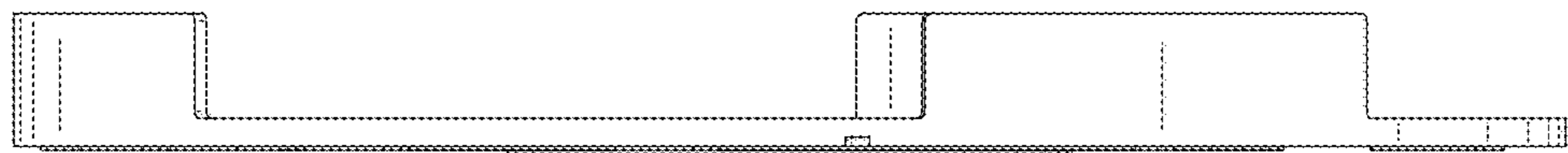


FIG. 3

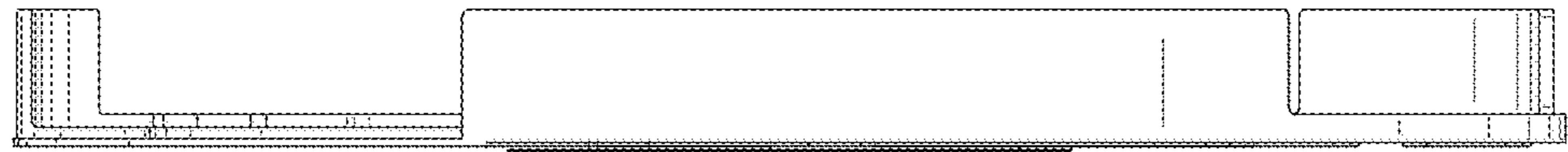


FIG. 4

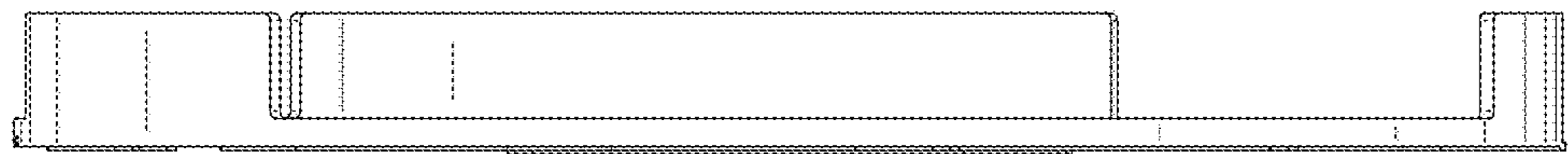


FIG. 5

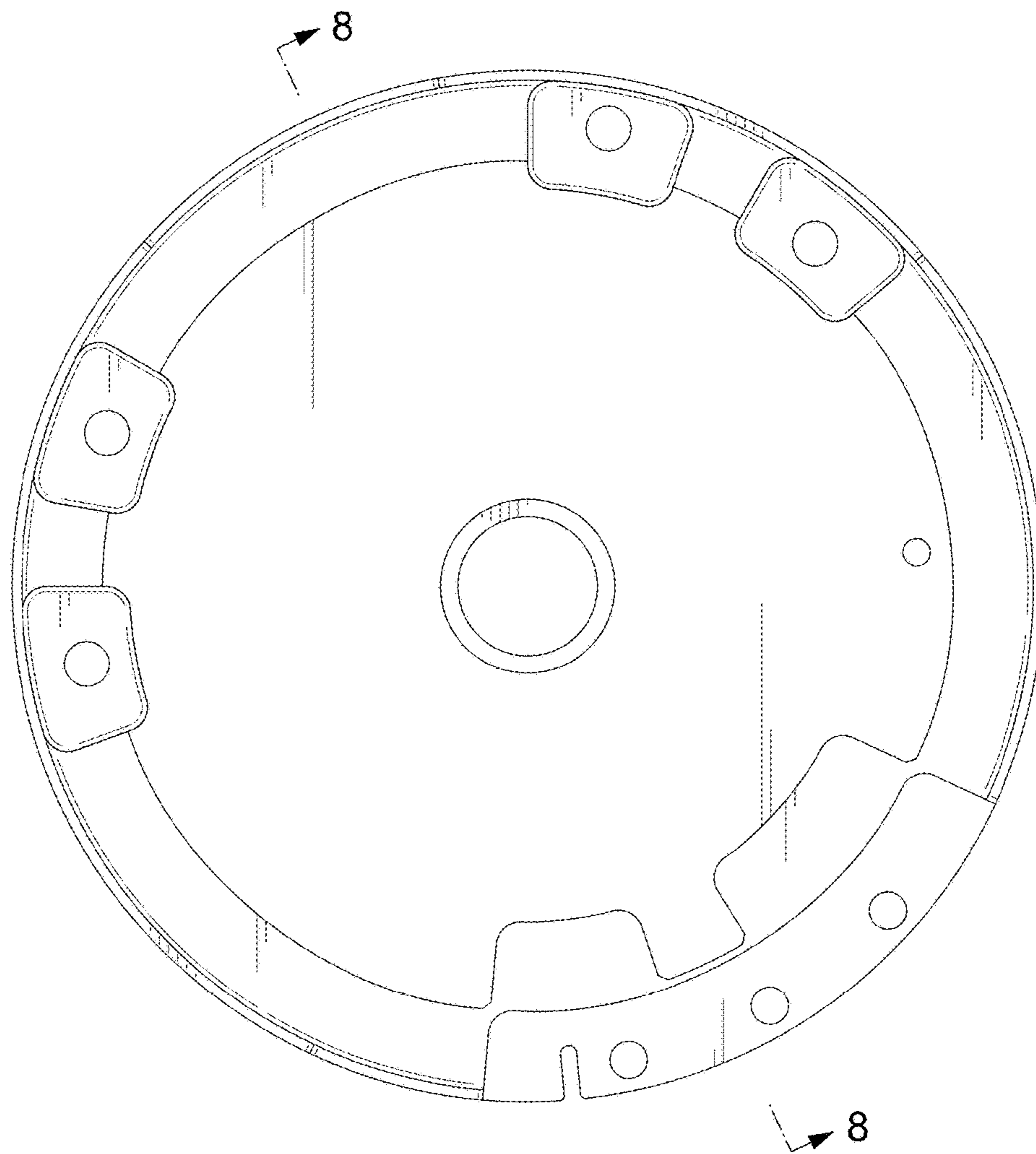


FIG. 6

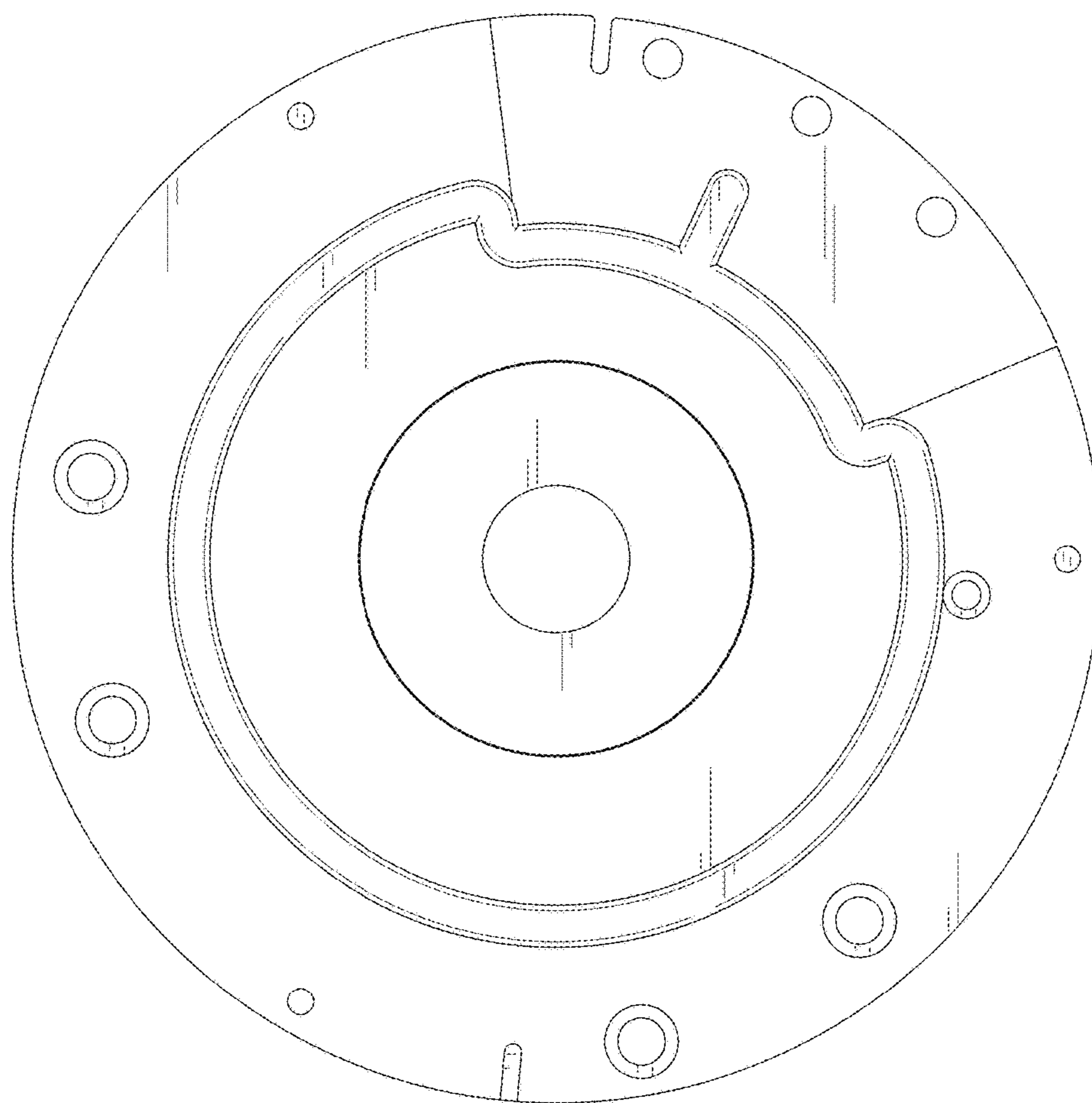


FIG. 7

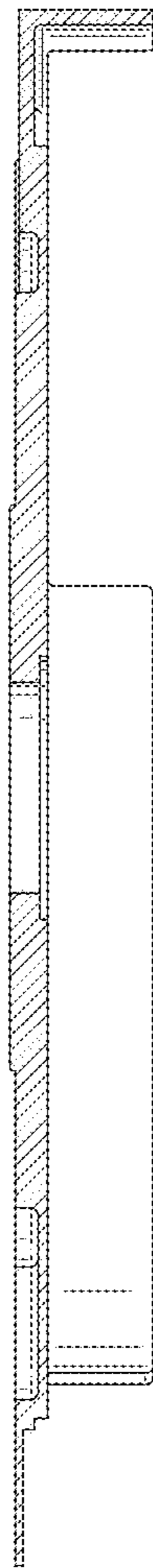


FIG. 8